

Adsorption of ACQ Components in Wood





Myung Jae Lee & Paul Cooper

Faculty of Forestry

University of Toronto



- ❖ Worldwide use of Alkaline Copper Quat (ACQ)
- ❖ Difficulty for high retention application
- ❖ Different fixation mechanism with CCA

Preservative Retentions by use category			
Use category		Service condition	Retention(kg/m ³)
UC 1,2		Interior construction	CCA: 4 ACQ: 4
UC 3		Exterior construction above ground	CCA: 4 ACQ: 4
UC 4		Ground contact or fresh water	CCA: 6.4-9.6 ACQ: 6.4-9.6
UC 5		Salt or brackish water	CCA: 40 ACQ: N.A

(AWPA 2006)

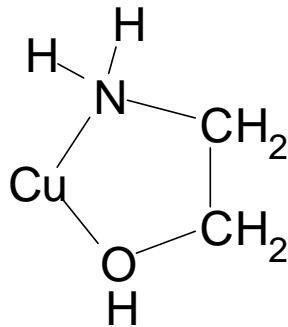
Canada pest management regulatory agency (PRMA)
: Ground contact 6.4 kg/m³

❖ ACQ

Composition (ACQ-D)		Weight ratio (%)
Ingredient	CuO	66.7
	Quat	33.3
Co-Solvent	Ethanolamine	183

(AWPA 2006)

❖ Cu-Mea complexes in solution

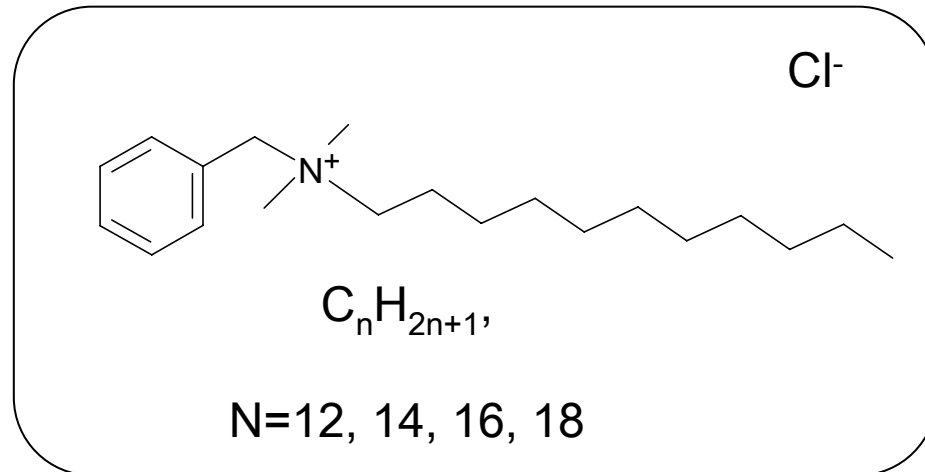


Cu complexes	Optimum pH	Formation %
Cu^{2+}	< 4.0	100
$[\text{CuMea}]^{2+}$	5.5	24
$[\text{Cu}(\text{Mea})_2]^{2+}$	6.8	24
$[\text{Cu}(\text{Mea})_3]^{2+}$	8.2	1
$[\text{Cu}(\text{Mea})_2]^+$	8.8	84
$[\text{Cu}(\text{Mea})_2]^0$	> 11.0	95

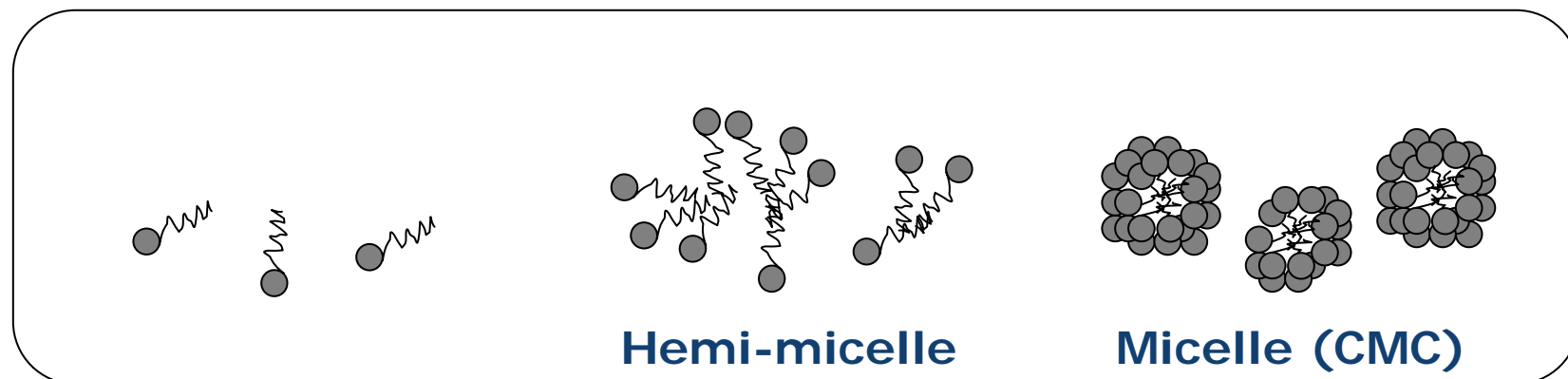
(Zhang and Kamdem 2000)

(Pankras and Cooper 2009)

❖ ADBAC (alkyl dimethyl benzyl ammonium chloride)



Hydrophilic
vs.
Hydrophobic



❖ **Copper**

- Cu adsorption capacity of wood
- Effective Cu-Mea complex for adsorption
- Cu adsorption mechanism in wood

❖ **Quat**

- Effect of micelle formation on quat adsorption
- Leaching resistance of micelle form adsorption
- Quat adsorption mechanism in wood

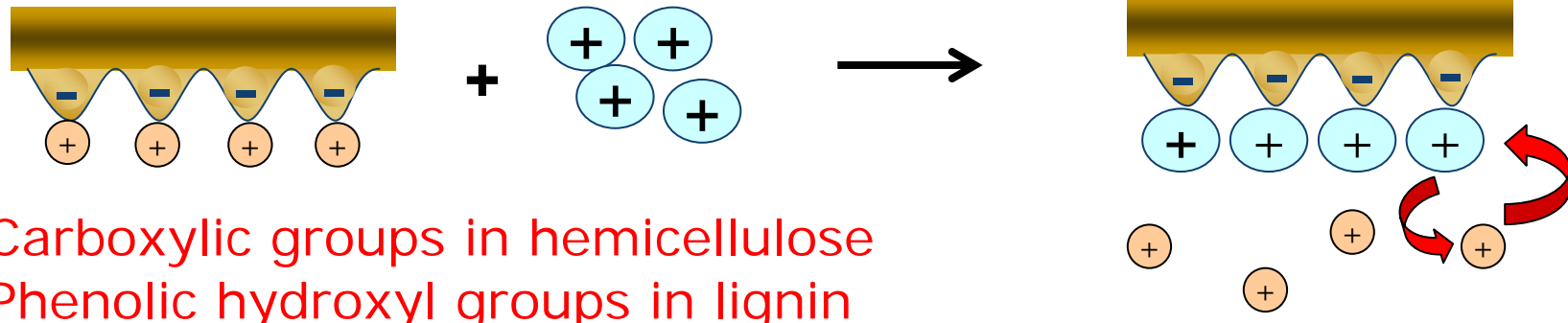
❖ Copper

Treated material	Sol. pH	Absorbent
NaOH	pH 2-13	Red pine dust
Cu-Mea (Lonza Inc.)	(HNO ₃)	3g
Cu-Dea/Cu-Tea	100ml sol.	(30-60mesh)

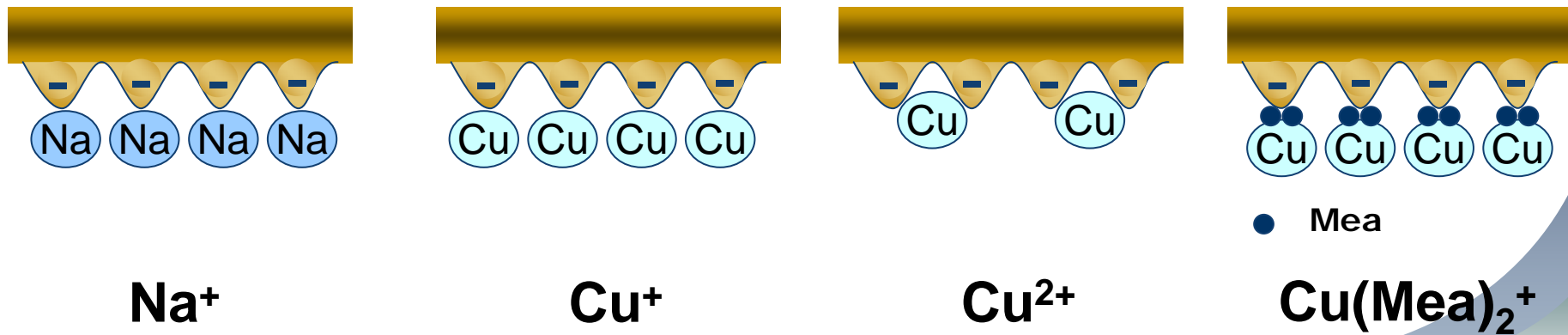
- Treating 48h and washing thoroughly
- Analysis Na and Cu by digestion followed by AAS and Mea with C/N analyzer

Experimental Method (Cont)

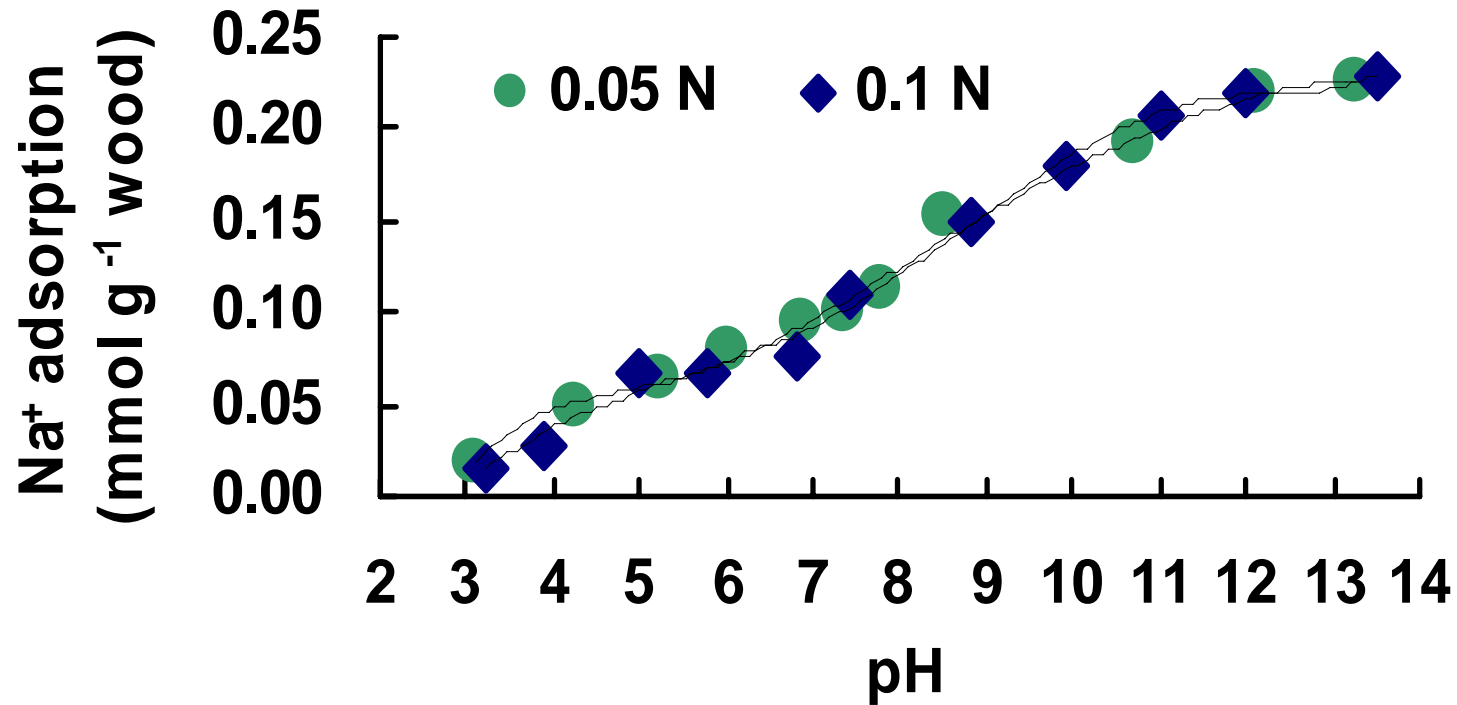
❖ Cation exchange reaction



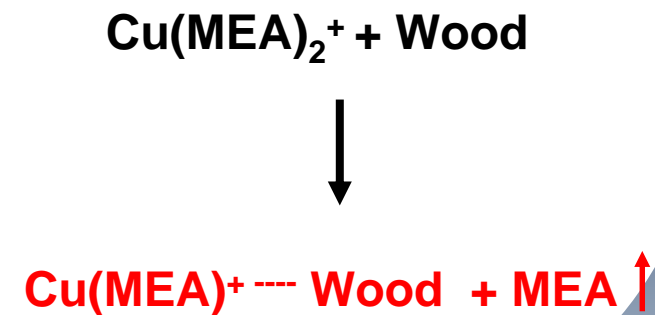
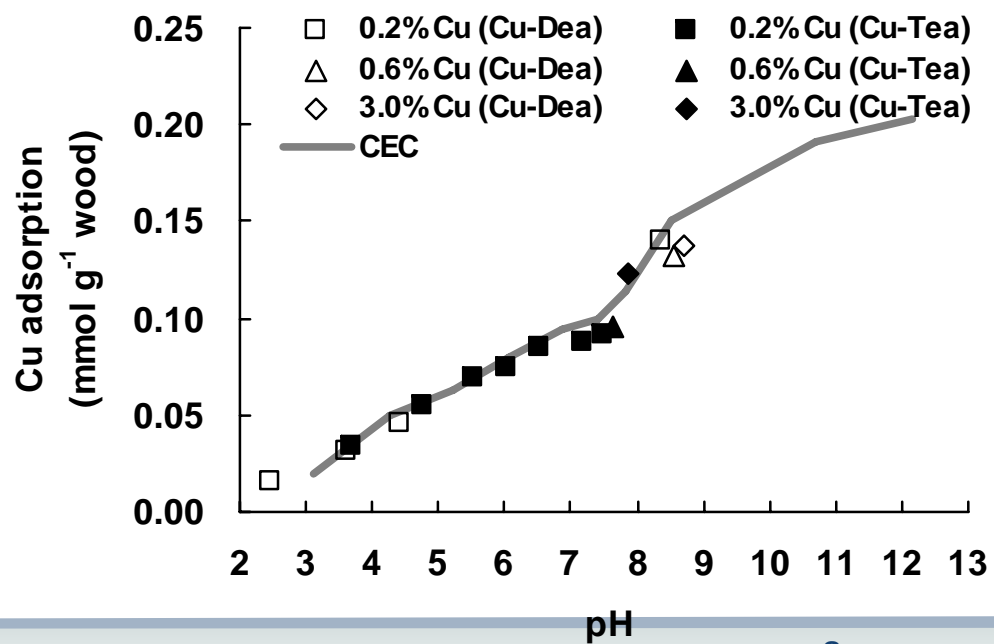
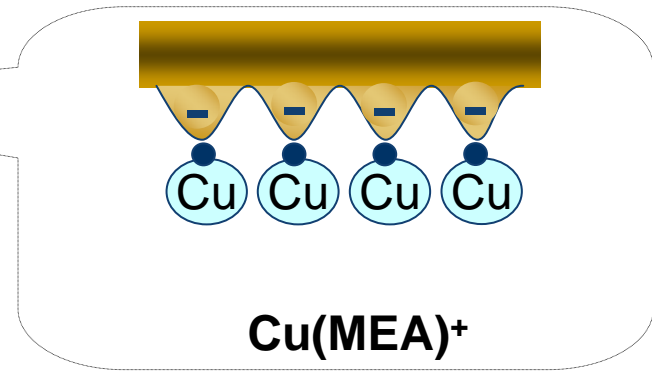
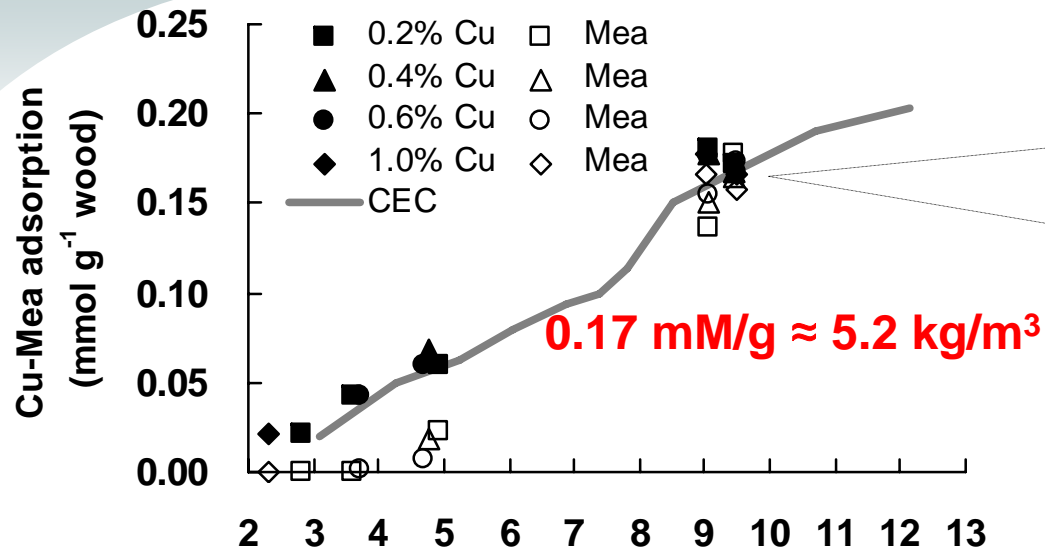
❖ Outline of Cu adsorption test



Results : Cation exchange capacity (CEC)

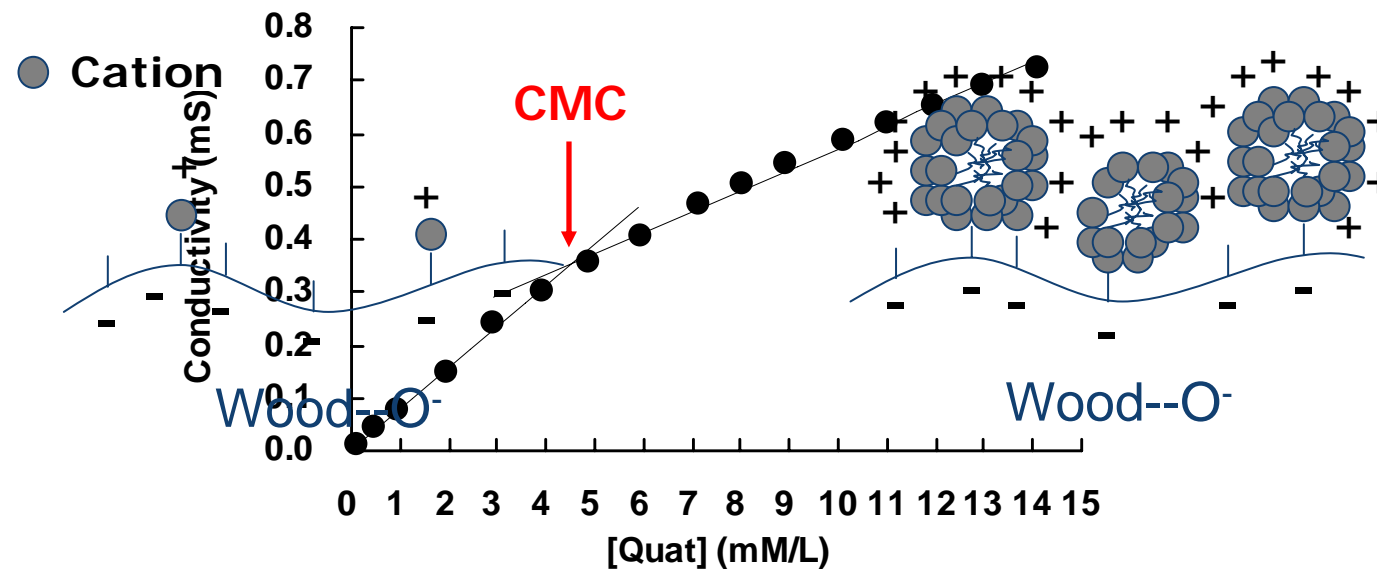


Results : Cu-Mea exchange capacity



❖ Quat

- CMC determination of quat by conductivity method (DW, 1.4% Mea, 2.8% Mea, 0.4% Cu-Mea)
- Zeta-potential of wood particle at different conc. (Model: Zeta plus, 400mesh particle, pH 5-7 at 22°C)



Experimental Method (Cont)

- Determination of quat adsorption capacity and leachability as a function of ADBAC (alkyl dimethyl benzyl ammonium chloride) conc.

Treated solution	ADBAC Conc.	pH	Treatment /leaching
ADBAC	0.005 -100	9.5 ± 0.2	5 / 10
ADBAC + 0.4% Cu	(mM/L)	(Mea)	(days)

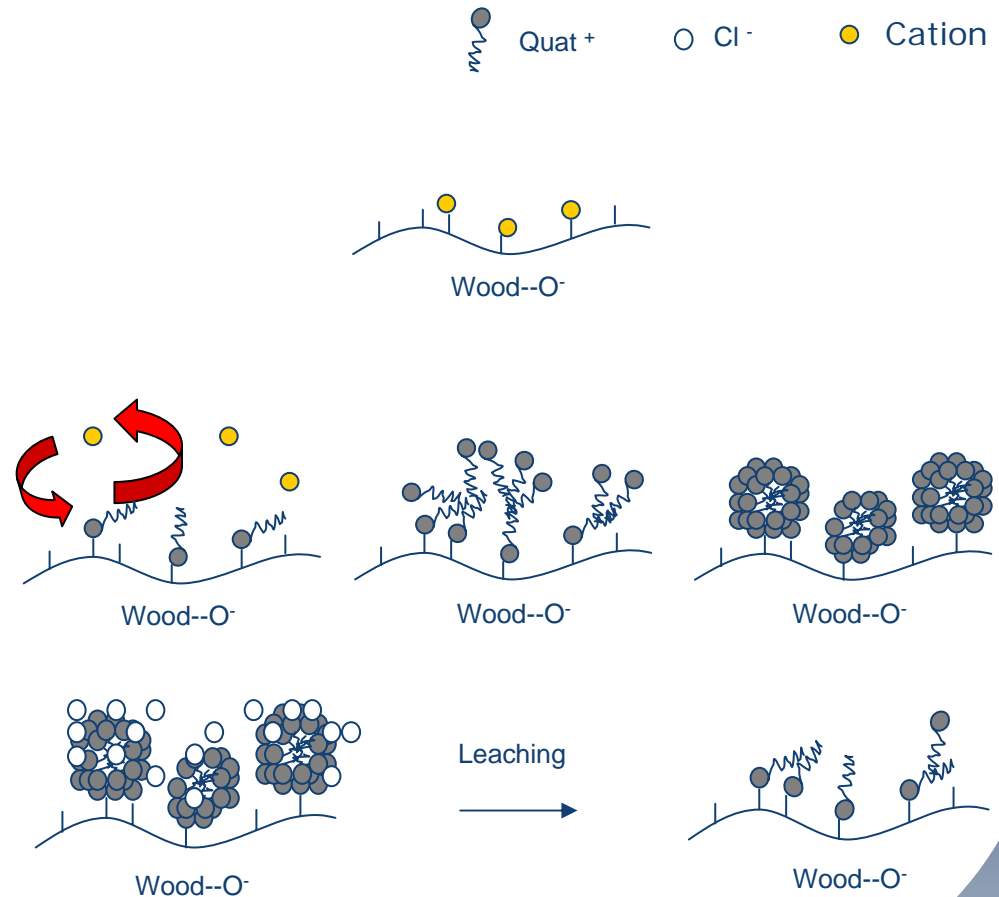
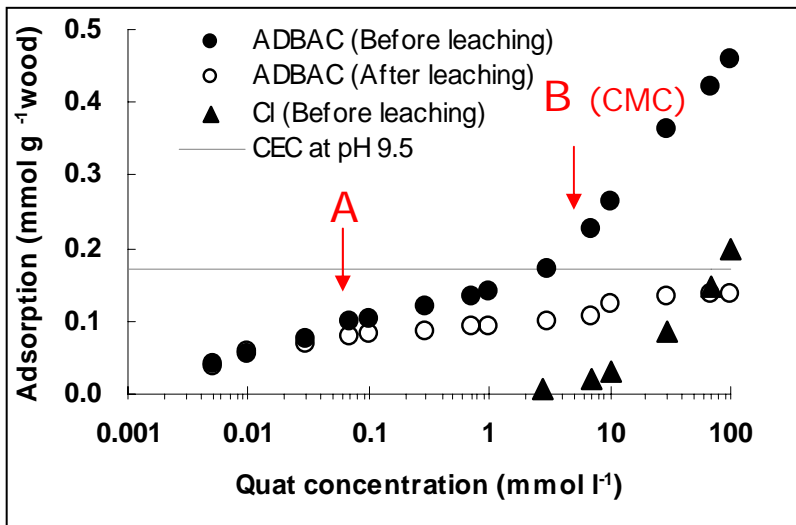
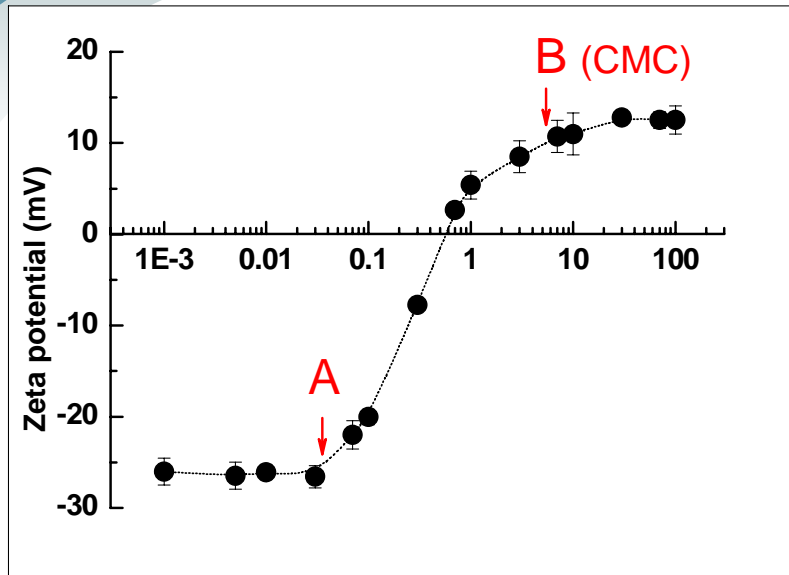
- Analysis quat and chloride by IC after extraction (AWPA A16-93)

Results : Critical micelle conc. (CMC)

Component	CMC _{ADBAC}		pH
	mmol l ⁻¹	%	
DW	4.57	0.160	5.6-7.2
Mea 1.4%	3.91	0.137	11.2-11.7
Mea 2.8%	2.74	0.096	11.7-11.9
Mea 1.4% + Cu 0.4%	0.77	0.027	8.9-9.2

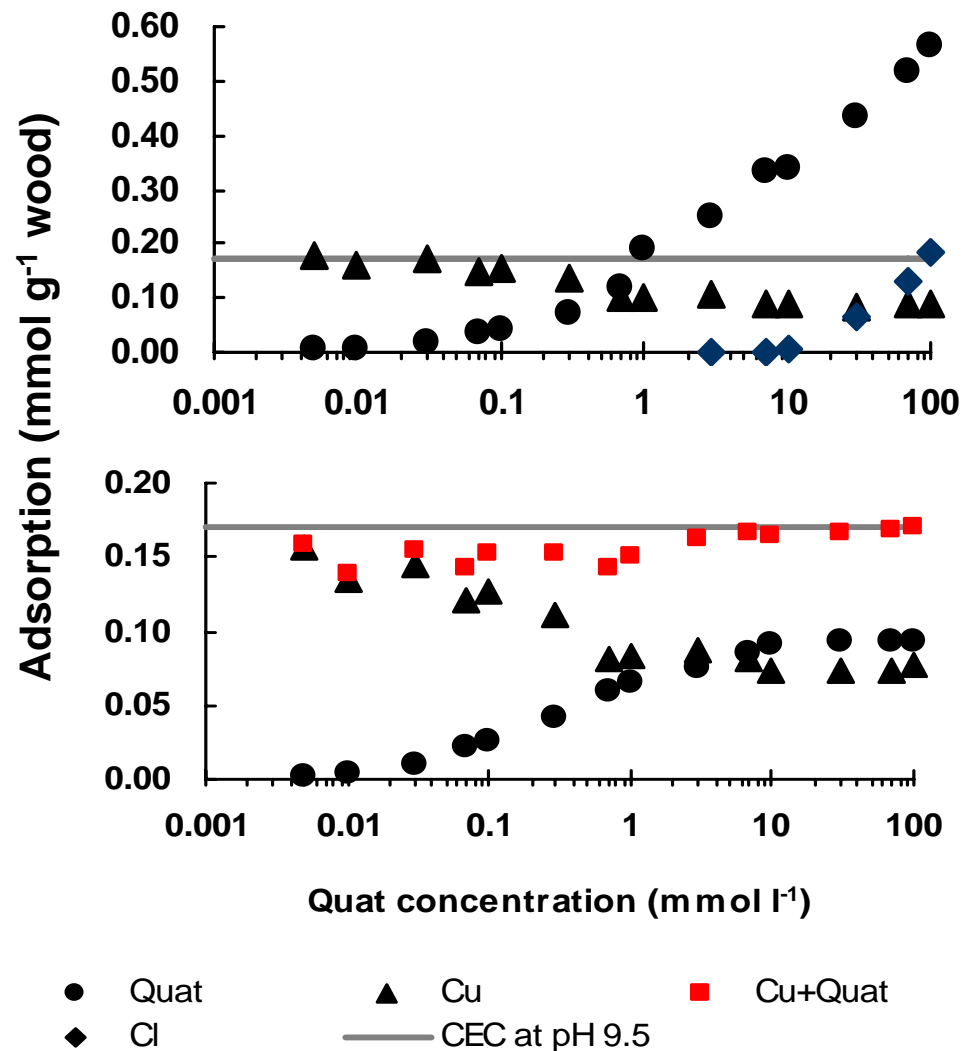
- CMC decreases by adding Mea and Cu
- 0.75 % ACQ sol. (≈ 0.25 % ADBAC) » CMC (0.027 %)
- **Micelle always present** in practical ACQ solution conc.

Results : Adsorption of Quat



Results : Competition in adsorption

❖ Quat adsorption in 0.4% Cu solution



- Wood has increasing CEC as pH increases
- Cu adsorption capacity in red pine was about 0.17 mM/g wood ($\approx 5.2 \text{ kg/m}^3$ as a CuO) at pH 9 as a form of $\text{Cu}(\text{Mea})^+$
- Quat showed two different adsorption mechanism:
 - Ion exchange reaction at low conc.
 - Aggregation form of adsorption at high conc. ($>\text{CMC}$)
- CMC decreased with adding Mea and Cu
- Anion (Cl^-) adsorption was only detected above CMC
- Aggregation form of quat and anion (Cl^-) has low leach resistance
- Quat adsorption does not quite reach the CEC
- Cu and Quat are in competition for the same adsorption sites

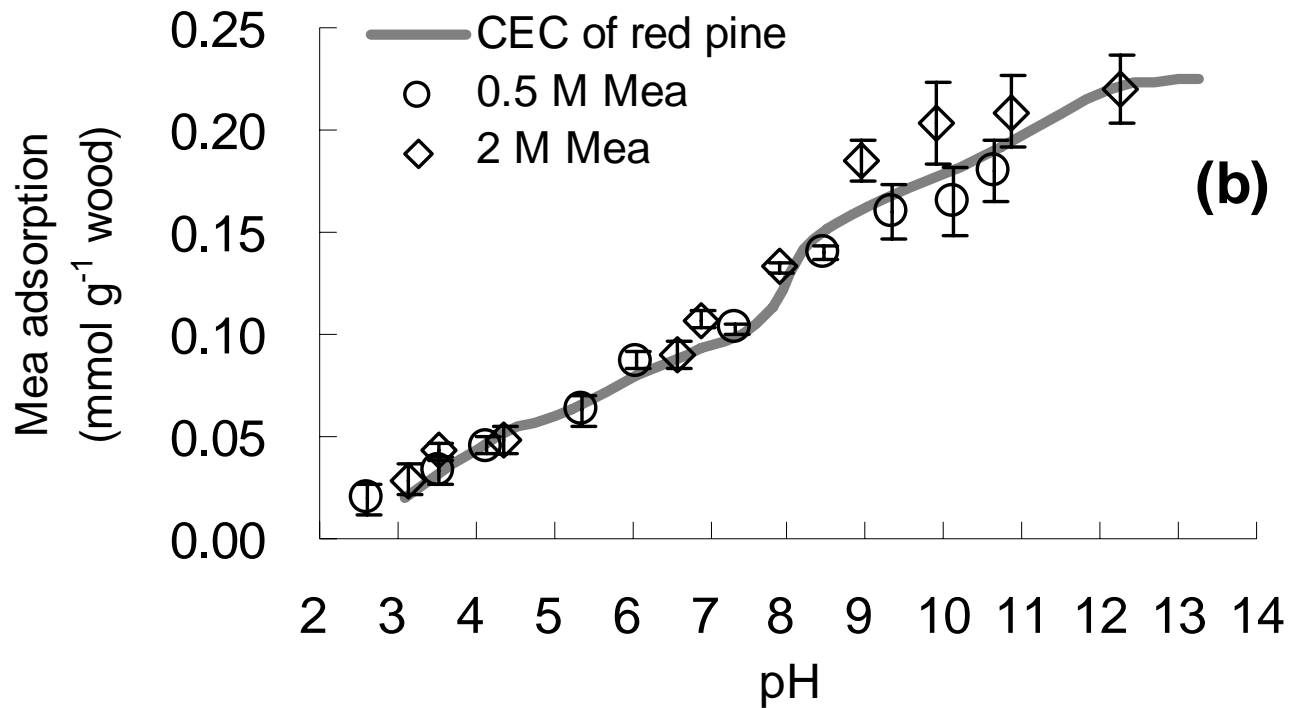
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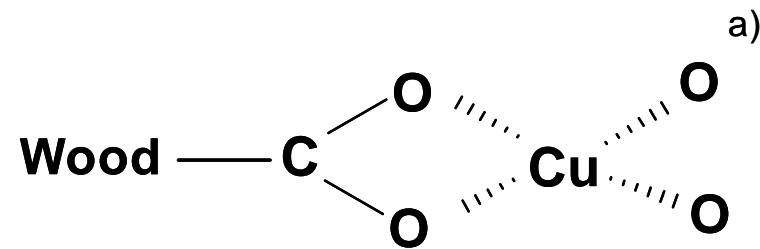
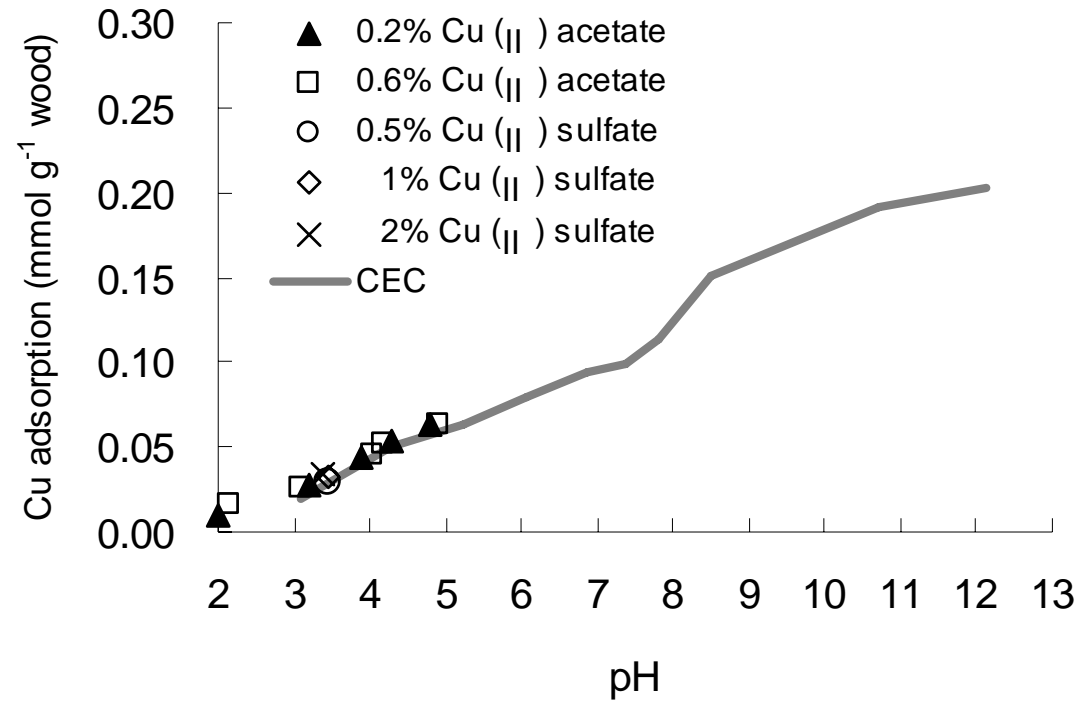
Owner; 2010-04-14

Thank You!

MEA adsorption and CEC

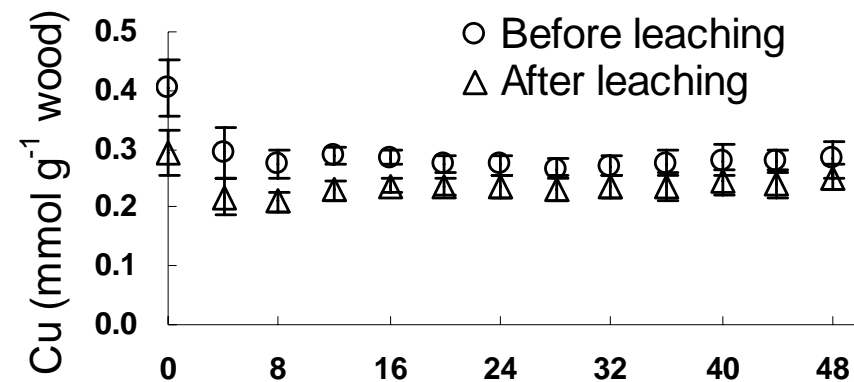


Cu adsorption (without MEA)



Red pine (30x60x100mm) treating with 2%

Longitudinal penetration



Radial penetration

